

FIG. 1 (PRIOR ART)



FIG. 2 (PRIOR ART)

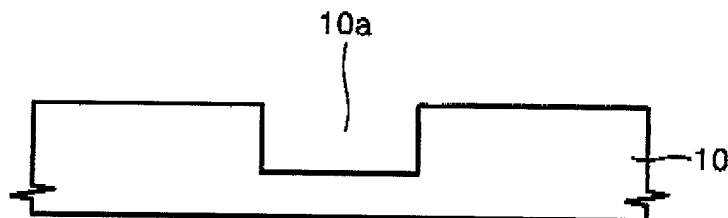
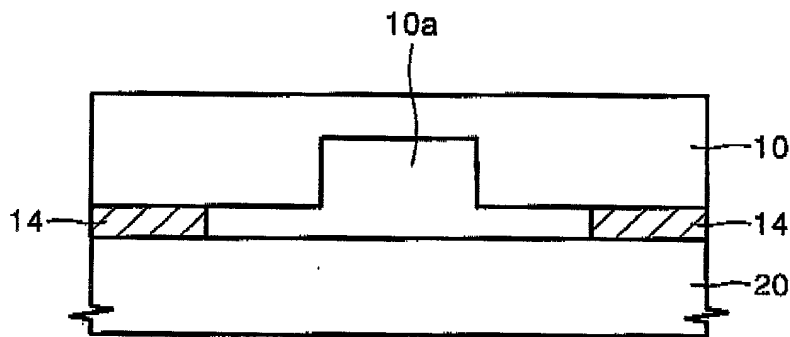


FIG. 3 (PRIOR ART)



Serial No Not Assigned Docket No 1751-300
Title Method of Through-Etching Substrate
Inventor Kyoung-dong Min, et al

FIG. 4 (PRIOR ART)

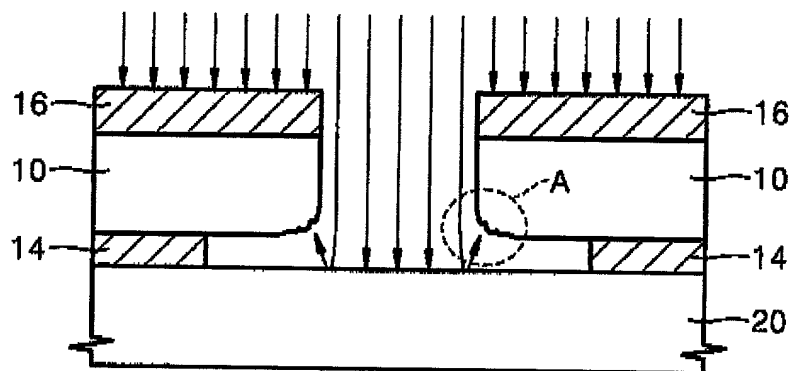


FIG. 5 (PRIOR ART)



Serial No Not Assigned Docket No 1751-300
Title. Method of Through-Etching Substrate
Inventor Kyoung-doug Min, et al

FIG. 6

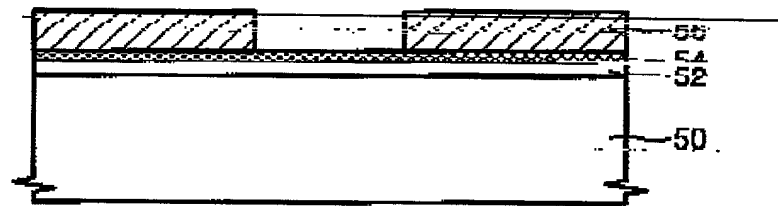


FIG. 7

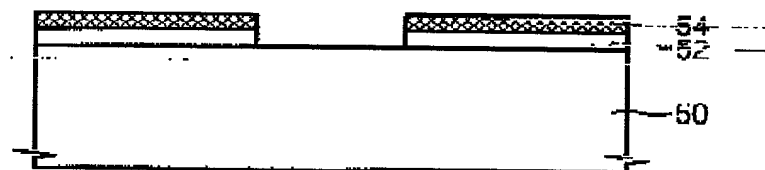
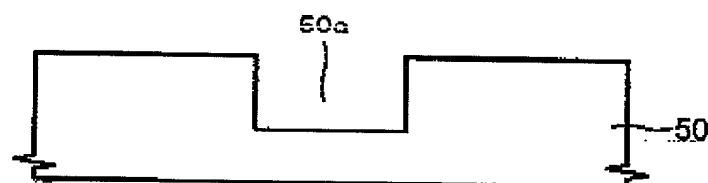


FIG. 8.



Serial No. Not Assigned Docket No. 1751-300
Title Method of Through-Etching Substrate
Inventor Kyoung-dong Min, et al.

FIG. 9

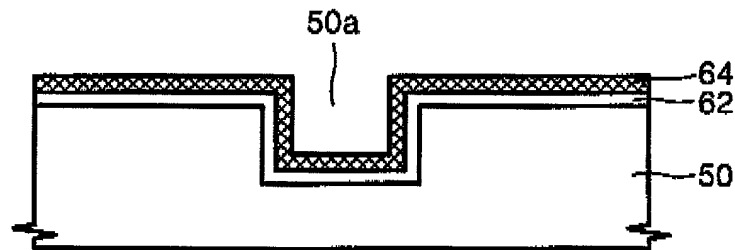


FIG. 10

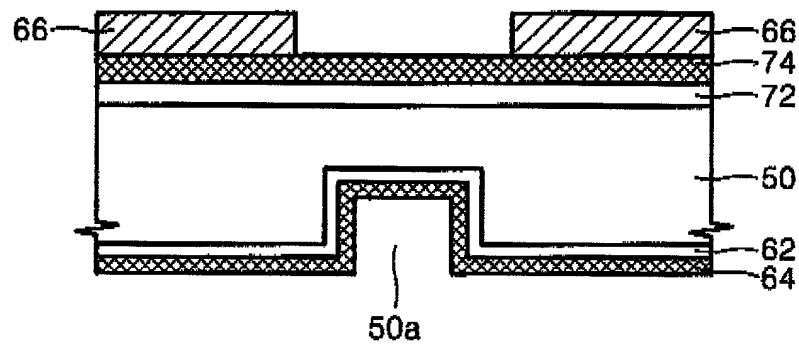
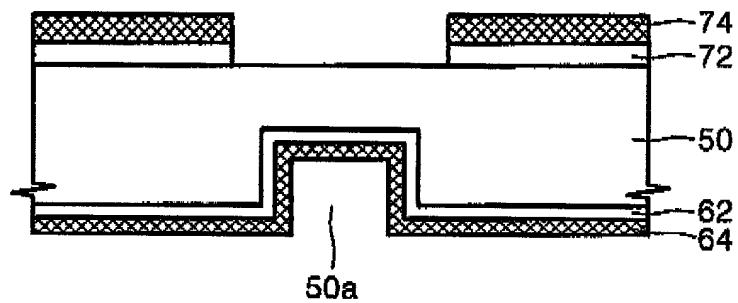


FIG. 11



Serial No. Not Assigned Docket No 1751-300
Title Method of Through-Etching Substrate
Inventor Kyoung-doug Min, et al.

FIG. 12

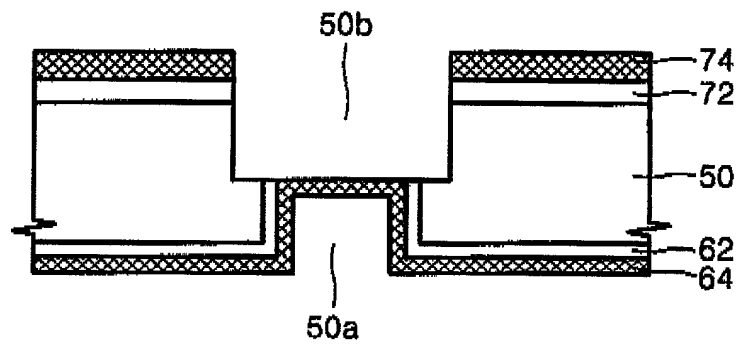
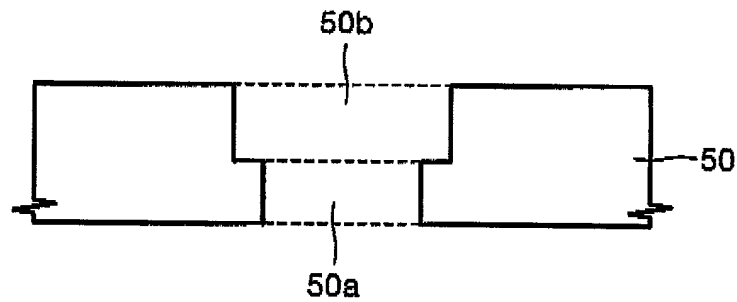


FIG. 13



Serial No Not Assigned Docket No 1751-300
Title Method of Through-Etching Substrate
Inventor Kyoung-doug Min, et al.

FIG. 14

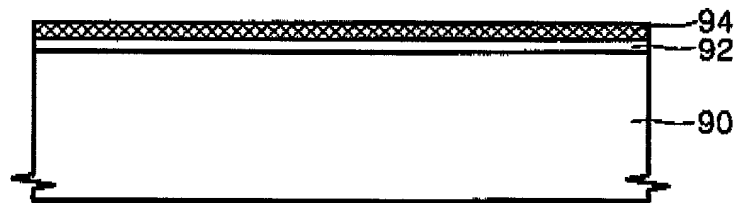
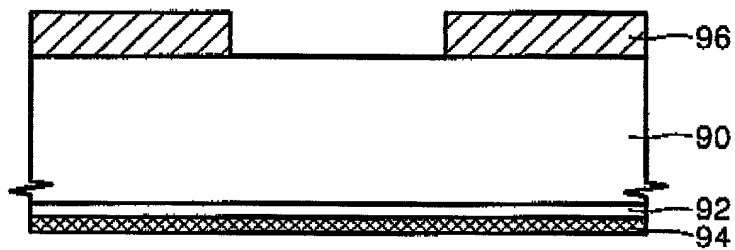


FIG. 15



Serial No Not Assigned Docket No. 1751-300
Title Method of Through-Etching Substrate
Inventor Kyoung-doug Min, et al.

FIG. 16

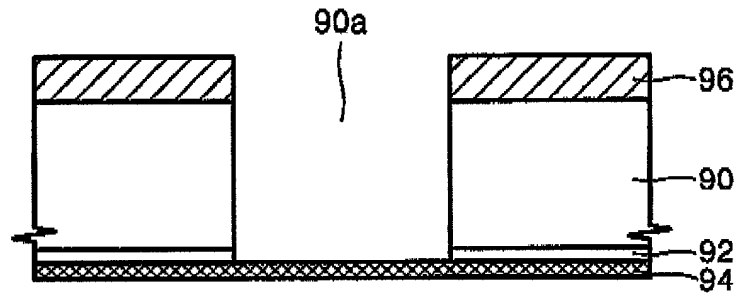


FIG. 17

